

**Amendments to the Claims:**

This listing of claims will replace the listing of claims as pending in the present application:

Listing of Claims:

Claim 1 (previously presented – Article 19): A copper or copper alloy target/copper alloy backing plate assembly for use in magnetron sputtering, wherein the copper alloy backing plate is formed from low beryllium copper alloy containing 0.2 to 0.5wt% of Be, or Cu-Ni-Si containing 2 to 4wt% of Ni and 0.3 to 0.9wt% of Si or Cu-Ni-Si-based alloy containing 2 to 4wt% of Ni and 0.3 to 0.9wt% of Si.

Claim 2 (original): The copper or copper alloy target/copper alloy backing plate assembly according to claim 1, wherein the Cu-Ni-Si-based alloy backing plate is formed from Cu-Ni-Si-based alloy containing 2 to 4wt% of Ni, 0.3 to 0.9wt% of Si, 0.1 to 0.9wt% of Cr or 0.1 to 0.9wt% of Mg.

Claims 3-6 (canceled).